



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC057N08NS3 G	Issued	13. April 2021
MA#	MA002561754		
Package	PG-TDSON-8-39	Weight*	113.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.666	3.22	3.22	32228	32228
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		428	
	non noble metal	copper	7440-50-8	48.649	42.78	42.83	427640	428196
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	502	502
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		695	
	plastics	epoxy resin	-	6.246	5.49		54901	
	inorganic material	silicondioxide	60676-86-0	33.205	29.19	34.75	291879	347475
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13362	13362
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1393	1393
solder	non noble metal	tin	7440-31-5	0.061	0.05		534	
	noble metal	silver	7440-22-4	0.076	0.07		667	
	non noble metal	lead	7439-92-1	2.899	2.55	2.67	25486	26687
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1319	
	non noble metal	copper	7440-50-8	16.910	14.86	15.00	148644	150157
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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